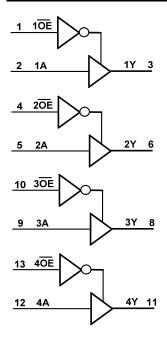


Pin Descriptions

Pin Number	Pin Name	Function
1	1 0E	Data Enable Input (active low)
2	1A	Data Input
3	1Y	Data Output
4	2 OE	Data Enable Input (active low)
5	2A	Data Input
6	2Y	Data Output
7	GND	Ground
8	3Y	Data Output
9	3A	Data Input
10	3 0E	Data Enable Input (active low)
11	4Y	Data Outp
12	4A	Data Input
13	40E	Data Enable Input (active low)
14	Vcc	Supply Voltage

Logic Diagram



Function Table

Inp	Output	
ŌĒ	Α	Y
L	Н	Н
L	L	L
Н	Х	Z



Absolute Maximum Ratings (Note 4) (@T_A = +25°C, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD CDM	Charged Device Model ESD Protection	1	KV
ESD MM	Machine Model ESD Protection	200	V
V _{CC}	Supply Voltage Range	-0.5 to +7.0	V
VI	Input Voltage Range note 3)	-0.5 to +7.0	V
I _{IK}	Input Clamp Current V _I < -0.5V or Vi > V _{CC} +0.5V	±20	mA
lok	Output Clamp Current $V_0 < -0.5V$ or $V_0 > V_{CC} +0.5V$	±20	mA
Io	Continuous Output Current -0.5V < V _O V _{CC} +0.5V	+/- 25	mA
Icc	Continuous Current Through V _{CC}	50	mA
I _{GND}	Continuous Current Through GND	-50	mA
TJ	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature	-65 to +150	°C
P _{TOT}	Total Power Dissipation	500	mW

Notes:

Recommended Operating Conditions (Note 6) (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	Supply Voltage		2.0	6.0	V
VI	Input Voltage		0	Vcc	V
Vo	Output Voltage		0	V _{CC}	V
		$V_{CC} = 2.0V$		625	
Δt/ΔV	Input Transition Rise or Fall Rate	$V_{CC} = 4.5V$		140	ns/V
		V _{CC} = 6.0V		85	
T _A	Operating Free-Air Temperature	_	-40	+125	°C

Note: 6. Unused inputs should be held at V_{CC} or Ground.

^{4.} Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

^{5.} Input Voltage cannot exceed V_{CC} to the extent the Maximum clamp current is exceeded.



Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Cumbal	Parameter	Test Conditions	V	T _A = -40°	C to +85°C	T _A = -40°C	to +125°C	Unit
Symbol	Parameter	rest Conditions	Vcc	Min	Max	Min	Max	
	I Bala I a cal I a a cal		2.0V	1.5		1.5		
V_{IH}	High-level Input Voltage		4.5V	3.15		3.15		V
	Voltage		6.0V	4.2		4.2		
	Law lavel lanut		2.0V		0.5		0.5	
V_{IL}	Low-level Input voltage		4.5V		1.35		1.35	V
	Tomago		6.0V		1.8		1.8	
		$I_{OH} = -20 \mu A$	2.0V	1.9		1.9		
		$I_{OH} = -20 \mu A$	4.5V	4.4		4.4		V
V_{OH}	High-level Output Voltage	I _{OH} = -20μA	6.0V	5.9		5.9		
	Voltago	$I_{OH} = -4.0 \text{mA}$	4.5V	3.84		3.7		
		I _{OH} = -5.2mA	6.0V	5.34		5.2		
		I _{OL} = 20μA	2.0V		0.1		0.1	
		I _{OL} = 20μA	4.5V		0.1		0.1	
V_{OL}	Low-level Output Voltage	I _{OL} = 20μA	6.0V		0.1		0.1	V
	Voltage	I _{OL} = 4mA	4.5V		0.33		0.44	
		I _{OL} = 5.2mA	6.0V		0.33		0.44	
l _{OZ}	Z State Leakage Current	V _O = 0 to 6.0V V _I = GND or 6.0V	6.0V		± 5.0		± 10	μΑ
II	Input Current	V _I = GND to 5.5V	6.0V		± 1		± 1	μA
I _{CC}	Supply Current	$V_I = GND \text{ or } V_{CC}, I_O = 0$	6.0V		20		40	μA

Switching Characteristics

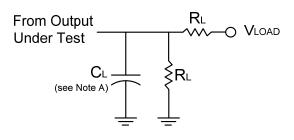
Cumbal	Parameter	Test	V		T _A = +25°C		-40°C to +85°C	-40°C to +125°C	Unit
Symbol	Parameter	conditions V _{CC}		Min	Тур.	Max	Max	Max	Ullit
	Danasastias	Figure 1	2.0V	_	30	100	125	150	
t_{PD}	Propagation Delay A _N to Y _N	Figure 1 C _I = 50 pF	4.5V	_	11	20	25	30	ns
	Delay AN IO IN	CL = 50 pr	6.0V	_	9	17	21	26	
		ime Figure 1	2.0V	_	41	125	155	190	
$t_{\sf EN}$	Enable Time		4.5V	_	15	25	31	38	ns
	OE _N to Y _N	C _L = 50 pF	6.0V	_	12	21	26	32	
		Figure 1	2.0V	_	41	125	155	190	
t _{DIS}	<u>Dis</u> able Time	Figure 1	4.5V	_	15	25	31	38	ns
	OE to Y _N	$C_L = 50 pF$	6.0V	_	12	21	26	32	
		Figure 4	2.0V	_	14	60	75	90	
t _t Transition time	ne Figure 1	4.5V	_	5	12	15	18	ns	
		$C_L = 50 \text{ pF}$	6.0V	_	4	10	13	15	

Operating Characteristics (@T_A = +25°C, unless otherwise specified.)

Parameter		Test Conditions	V _{CC} = 6V Typ	Unit
C _{pd}	Power Dissipation Capacitance per Gate	f = 1MHz	22	pF
Cı	Input Capacitance	$V_I = V_{CC} - \text{or GND}$	4	pF



Parameter Measurement Information



TEST	Condition
t _{PLZ} (see Notes D and E)	Vload
t _{PZL} (see Notes D and F)	Vload

V	Inputs		V	V		В	V Δ
V _{CC}	VI	t_r/t_f	V _M	V _{LOAD}	CL	KL	VΔ
2.0V to 6.0V	V _{CC}	≤3ns	V _{CC} /2	2 X V _{CC}	15,50 pF	2 ΚΩ	10% of V _{CC}

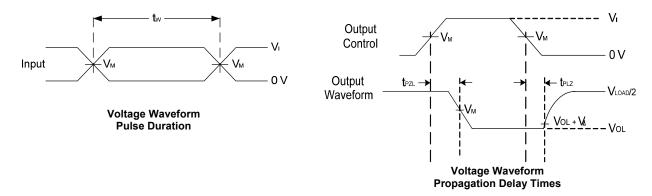


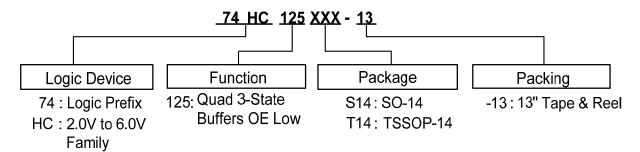
Figure 1 Load Circuit and Voltage Waveforms

Notes: A. Includes test lead and test apparatus capacitance.

- B. All pulses are supplied at pulse repetition rate ≤ 1 MHz.
- C. The inputs are measured one at a time with one transition per measurement.
- D. For the 3 state device t_{PLZ} and t_{PZL} are the same as t_{PD} .
- E. t_{PZL} is measured at V_{M} .
- D. t_{PLZ} is measured at V_{OL} + V_{Δ} .



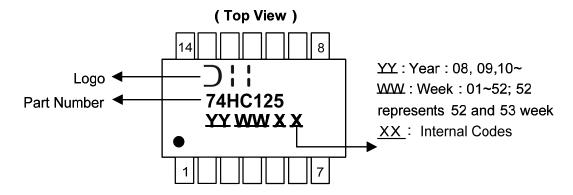
Ordering Information



	Device	Package Code	Packaging	7" Tape	and Reel
	Device	Package Code	Packaging	Quantity	Part Number Suffix
free Green	74HC125S14-13	S14	SO-14	2500/Tape & Reel	-13
Pb Hree Green	74HC125T14-13	T14	TSSOP-14	2500/Tape & Reel	-13

Marking Information

(1) SO-14, TSSOP-14



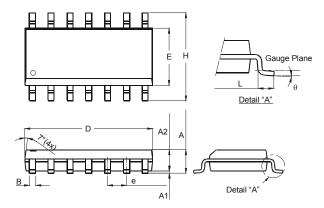
Part Number	Package
74HC125S14	SO-14
74HC125T14	TSSOP-14



Package Outline Dimensions (All dimensions in mm.)

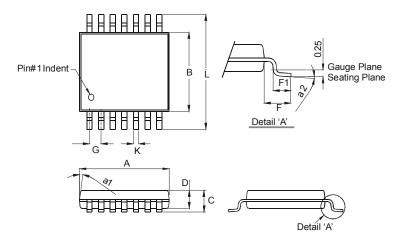
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

Package Type: SO-14



	SO-14				
Dim	Min	Max			
Α	1.47	1.73			
A1	0.10	0.25			
A2	1.45 Typ				
В	0.33	0.51			
D	8.53	8.74			
Е	3.80	3.99			
е	1.27	Тур			
Н	5.80	6.20			
L	0.38	1.27			
θ	0°	8°			
All Di	All Dimensions in mm				

Package Type: TSSOP-14



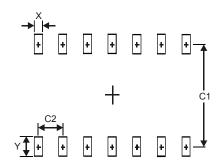
TSSOP-14			
Dim	Min	Max	
a1	7° (4X)		
a2	0°	8°	
Α	4.9	5.10	
В	4.30	4.50	
O		1.2	
D	8.0	1.05	
F	1.00 Typ		
F1	0.45	0.75	
O	0.65 Typ		
K	0.19	0.30	
L	6.40 Typ		
All Dimensions in mm			



Suggested Pad Layout

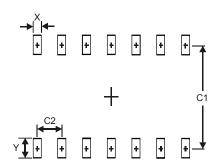
Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.

Package Type: SO-14



Dimensions	Value (in mm)
Х	0.60
Y	1.50
C1	5.4
C2	1.27

Package Type: TSSOP-14



Dimensions	Value (in mm)
Х	0.45
Y	1.45
C1	5.9
C2	0.65



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